

## **RB551V-30S**

# **Schottky Barrier Diode**

#### Features

- For Power Supply
- Moisture Sensitivity Level 1
- Low Voltage, Low Inductance

#### **Mechanical Data**

- Package: SOD-323
- Terminals: Tin plated leads, solderable per
- J-STD-002 and JESD22-B102
- Polarity: Cathode line denotes the cathode end
- Marking: DS

### ■Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE
Peak Repetitive Reverse Voltage	Vrrm	V		30
DC Blocking Voltage	V <sub>R</sub>	V	I <sub>R</sub> =100uA	20
Non-repetitive Peak forward surge current	I <sub>FSM</sub>	А	tp=8.3ms, half sine	2
Average forward current	IFAV	А		0.5
Power Dissipation	PD	mW		200
Thermal Resisitance Junction to Ambient Air	R <sub>θJA</sub>	°C/W		500
Junction temperature	Тj	°C		125
Storage temperature range	T <sub>stg</sub>	°C		-55 to +150

\*Part mounted on FR-4 board with recommended pad layout.

#### ■Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
RB551V-30S	F2	Approximate 0.0048	3000	30000	120000	7" reel

Shanghai Sunco Electronics Co., Ltd

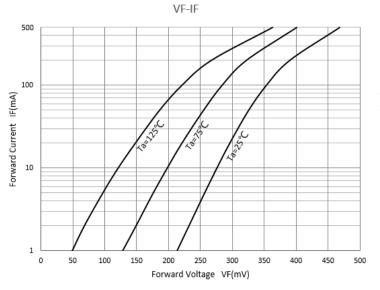


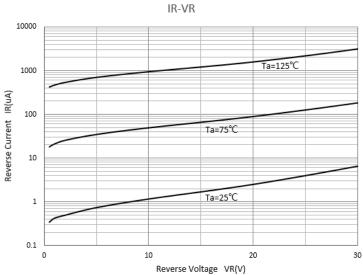
# **RB551V-30S**

### **Electrical Characteristics** (T<sub>a</sub>=25°C Unless otherwise specified)

PARAMETER	Symbol	UNIT	Conditions	Min.	Тур.	Max.
Forward Voltage *	V <sub>F</sub>	V	I <sub>F</sub> =0.1A	-	-	0.37
			I <sub>F</sub> =0.5A	-	-	0.47
Reverse Leakage Current	I <sub>R</sub>	uA	V <sub>R</sub> =20V	-	-	100

## Typical Characteristics



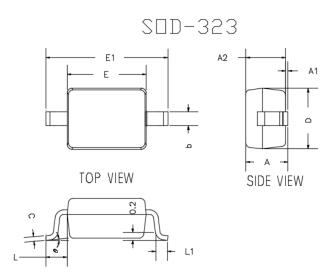


Cj-VR 100 Capacitance Between Terminals C<sub>j</sub>(pF) 0 5 0 10 15 20 25 30

Reverse Voltage VR(V)



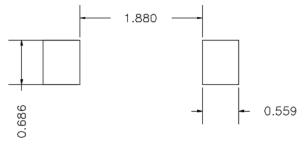
### Outline Dimensions



DIMENSIONS					
DIM	INC	HES	ММ		
	MIN	MAX	MN	MAX	
А		0.0393		1.0000	
A1	0.0000	0.0039	0.0000	0.1000	
A2	0.0314	0.0354	0.8000	0.9000	
b	0.0098	0.0157	0.2500	0.4000	
c	0.0031	0.0059	0.0800	0.1500	
D	0.0472	0.0551	1.2000	1.4000	
E	0.0629	0.0709	1.6000	1.8000	
E1	0.0984	0.1063	2.5000	2,7000	
L	0.018	7TYP	0.475TYP		
L1	0.0098	0.0157	0.250	0.400	
0	0°	8°	0°	8*	

SIDE VIEW

### Soldering Footprint



UNIT: mm SUGGESTED SOLDER PAD LAYOUT

Shanghai Sunco Electronics Co., Ltd



## **RB551V-30S**

### Disclaimer

The information presented in this document is for reference only. Shanghai Sunco Electronics Co., Ltd reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Russiansunco or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website http:// www.russiansunco.com , or consult your nearest Russiansunco's sales office for further assistance.